

Fig. 2a

$$(CH_2)_x - O - C - CH = CH_2$$
 $(CH_2)_x - O - C - CH = CH_2$
 $(CH_2)_x - O - C - CH = CH_2$

Fig. 2b
$$(CH_2)_{x}$$
-O-C- $CH=CH_2$ $H_2C=CH-C-O-(CH_2)_{x}$ $(H_5C_2O)_2Si$ (Si)

Fig. 2c

$$F_2C$$
 $CF_2 CF_2 CF$

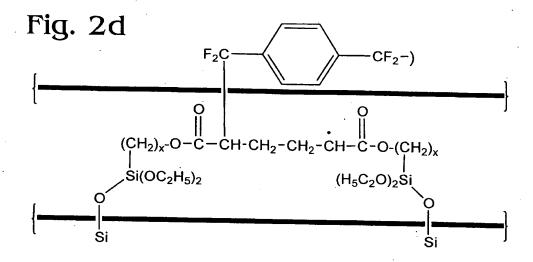
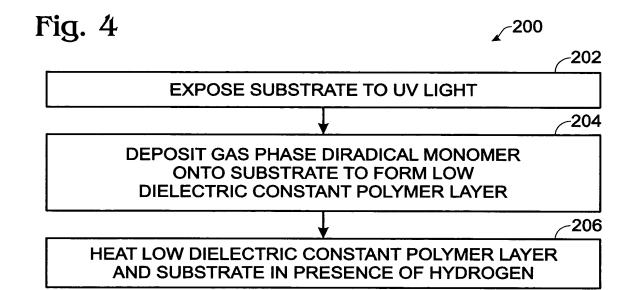
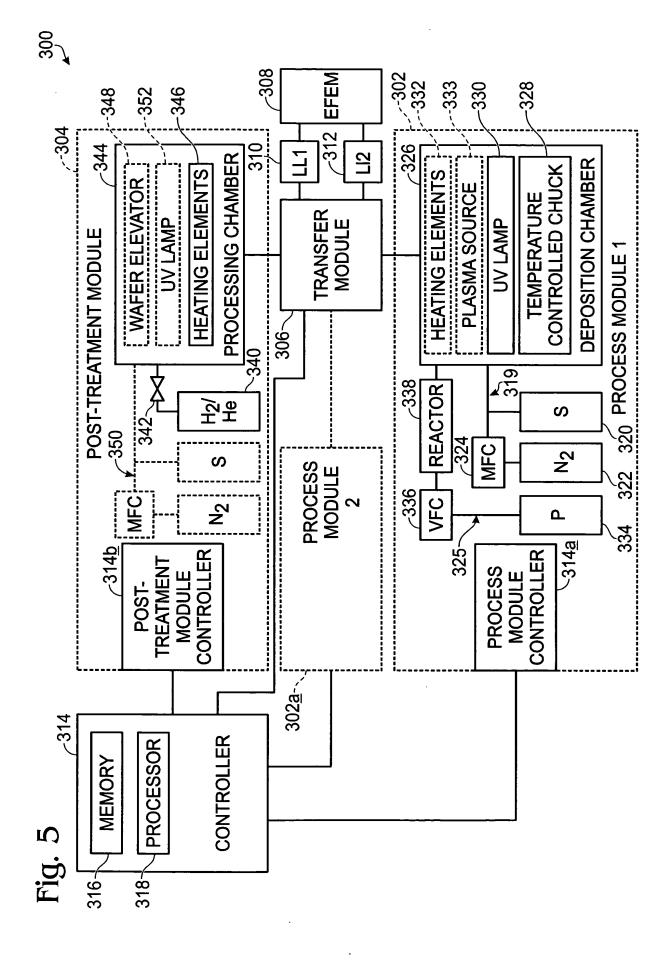
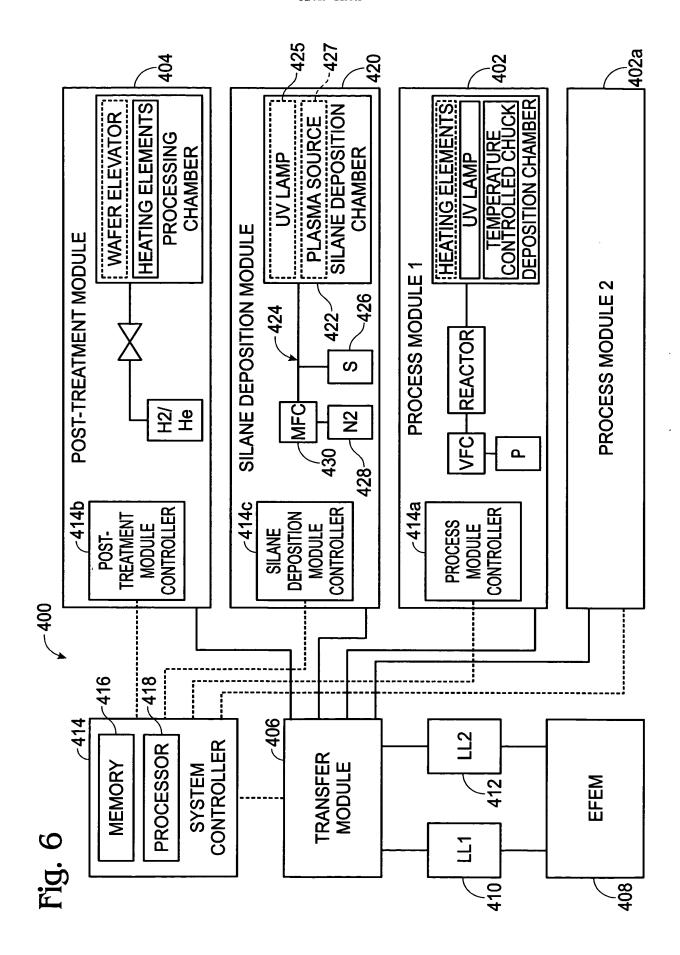


Fig. 2e
$$\frac{250 \text{ °C}}{300 \text{ °C}}$$
 $\frac{300 \text{ °C}}{300 \text{ °C}}$ $\frac{300 \text{ °C}}{300 \text{$

SYSTEM FOR FORMING COMPOSITE POLYMER DIELECTRIC FILM Inventors: Chung J. Lee, Atul Kumar, Chieh Chen and Yuri Pikovsky Attorney: M. Matthews Hall Telephone: (503) 224-6655 Our File – DSI 302







5/77

SYSTEM FOR FORMING COMPOSITE POLYMER DIELECTRIC FILM Inventors: Chung J. Lee, Atul Kumar, Chieh Chen and Yuri Pikovsky Attorney: M. Matthews Hall

Telephone: (503) 224-6655

Our File – DSI 302

